

### **Project objectives:**

To develop the Charge Trapping Technology for very high density Non Volatile Memories for mass storage, targeting the 22 nm technology node.

Start date: January 1st, 2008

Duration: 3 years

#### Memories for the mobile world

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During the last 15 years, ICTs have provided a number of radically new devices / techno-toys that have improved the daily life of the EU citizen: mobile phone, digital camera, MP3 players, PC, PDA, credit cards, video on discs, flat screen, HD TV, fast communications (ADSL)...



Solid-state memories are the preferred solution for mobile applications. Their main advantages are the use of consolidated technology, the lack of any mechanical parts, which results in stronger ruggedness, lighter weight, smaller form-factor, better reliability and, above all, **lower power dissipation**.

And solid-state mass-storage today means NAND Flash memories

# What are Flash?



Flash memory is non-volatile computer memory that can be electrically erased and reprogrammed. It is a technology that is primarily used in memory cards and LISB flash drives for general storage and transfer of

data between computers and other digital products. Flash memory is non-volatile, which means that no power is needed to maintain the information stored in the chip (Wikipedia)



#### Pushing the limit of Flash

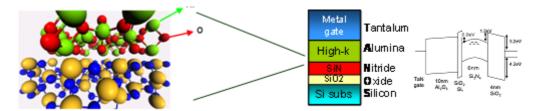
NAND Flash is by far the dominant technology for solid-state mass-storage. However, the floating gate concept is predicted to face technological limits around the 32nm node. The main physical limits that prevent further scaling of the cells are:

- cell to cell interference, due to the parasitic capacitive coupling among neighbouring floating gates;
- low coupling ratio with the control gate, which results also in a small stored charge.

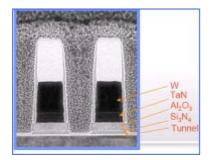
year	2004	2006	2008	2011	2014
Node	90 nm	65nm	45nm	32nm	22 nm
NOR					
NAND					

On the other side, trap-related leakage currents in the dielectrics prevent any scaling of the cell dielectrics, which could relieve this issue. Further reduction of cell size will increase the requirements for error correction beyond the feasibility limits.

The most promising option to overcome these scaling limitations, while retaining the very high integration density of NAND Flash architecture seems to be the replacement of the conventional floating gate with a charge trapping layer.



#### **Project Approach**



The consortium is build around two major European semiconductor companies, Numonyx and Qimonda, with a strong experience and a technical leadership in different types of memories (DRAM for Qimonda and NOR Flash for Numonyx) and have a great interest for NAND Flash memories, because of their strategic importance for a variety of applications.

The consortium includes a balanced combination of all types of research performers: Large Industry, Small and Medium

Industry, Research Centres and Universities

The key to the success of the project will be in the tight integration of allocated resources and their focalization, inside 7 Work Packages:

WP0 Management

WP1 Material Development

WP2 Cell Architecture

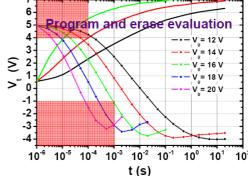
**WP3 Process Integration** 

WP4 Demonstrator

WP5 Characterization & Reliability

WP6 Higher density Architectures

WP7 Dissemination & Training



## FP7 Contract 214431 GOSSAMER project executive summary

